

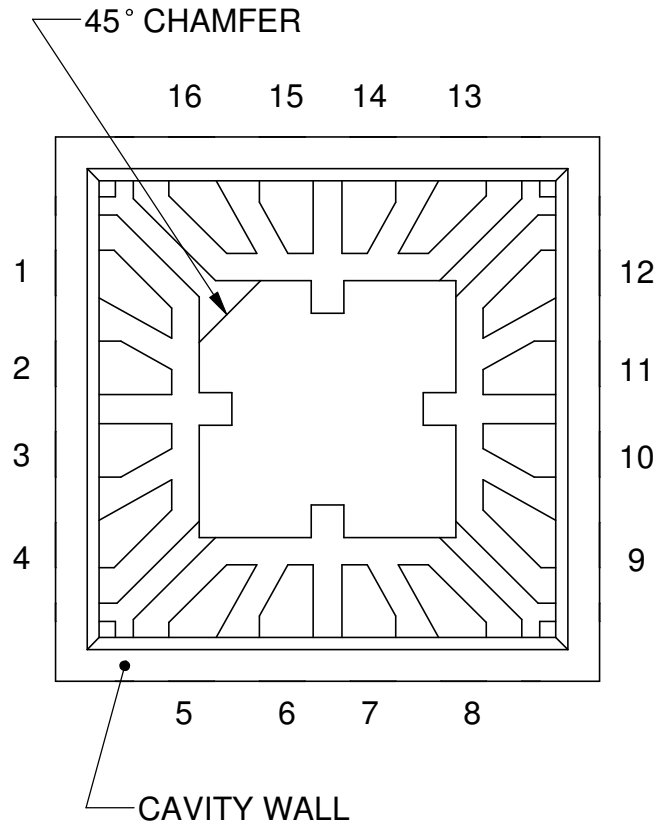
Notes: (Unless Otherwise Specified).

- 1) BODY: PLASTIC, SEMICONDUCTOR GRADE.
- 2) LEAD FRAME: COPPER, C-194 F/H.
- 3) LEAD FRAME PLATING: Ni, Pd, Au.
- 4) FRAME THICKNESS: 0.203MM.
- 5) DIE PAD: 1.4 X 1.4MM.
- 6) JEDEC OUTLINE: MO-220.
- 7) DIMENSIONS: MM.

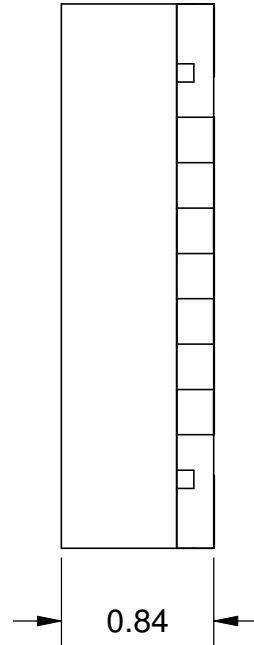
TOLERANCE UNLESS NOTED		APPROVALS	DATE				
X.XX	+/- 0.01	DRAWN J. Hines	6/14/2010	TITLE 16-LEAD 3mm P=0.5mm M-QFN CAVITY PACKAGE			
X.XXX	+/- 0.005						
X.XXXX	+/- 0.0005						
ANGLES +/- 0.5°		ENG					
ALL DIMENSIONS IN		MFG					
<input checked="" type="checkbox"/> INCHES <input type="checkbox"/> MILLIMETERS		QA		SCALE	SIZE	DRAWING NO.	REV
THIRD ANGLE PROJECTION		CUST		24:1	A	451660	A
		REVISED		DO NOT SCALE DRAWING			SHEET 1 OF 4

PIN LOCATIONS

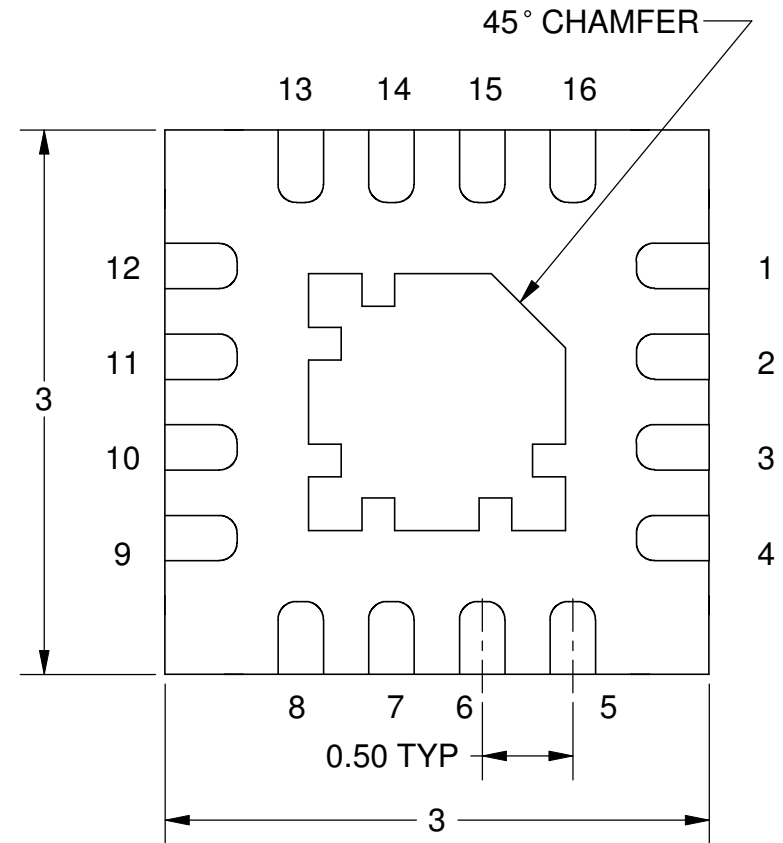
TOP VIEW



SIDE VIEW (BEFORE LID ATTACH)



BOTTOM VIEW



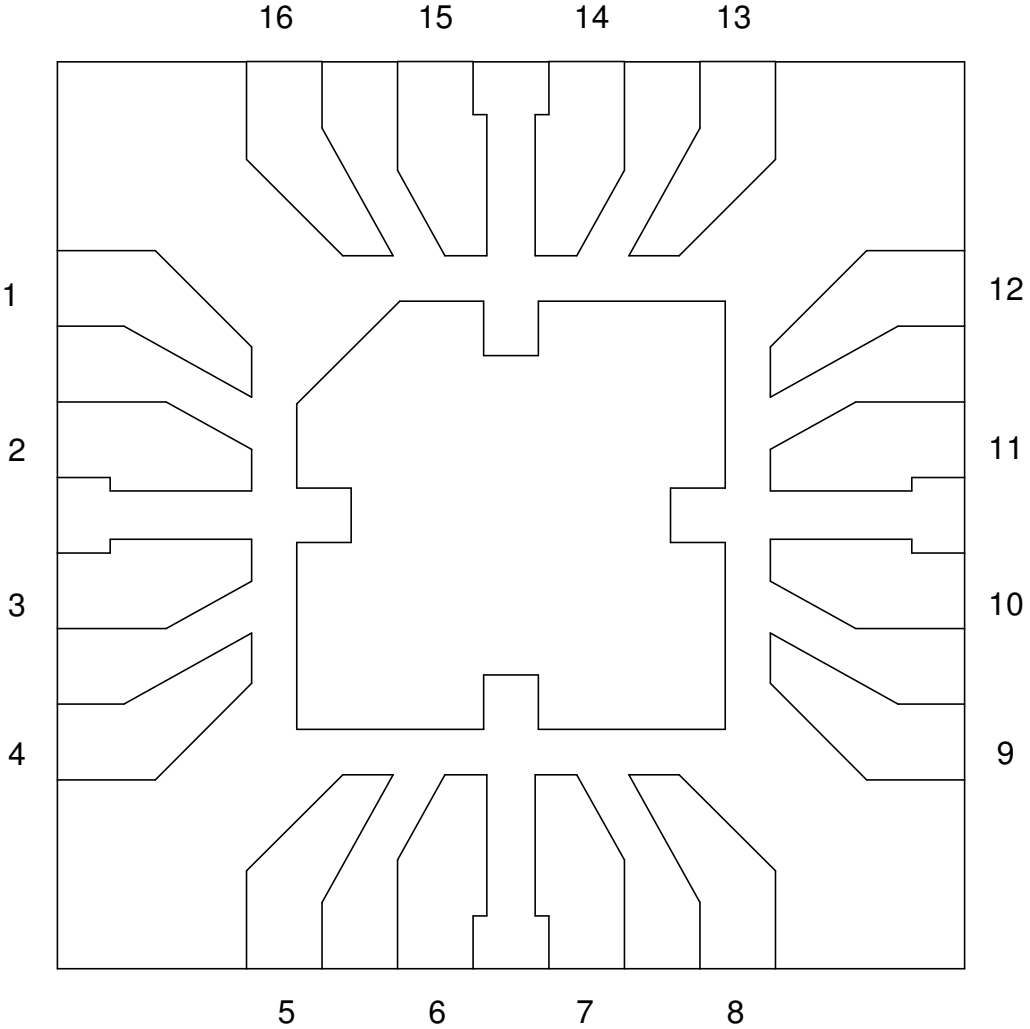
TITLE 16-LEAD 3mm P=0.5 mm
M-QFN CAVITY PACKAGE


SCALE 24:1	SIZE A	DRAWING NO. 451660	REV A
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DO NOT SCALE DRAWING

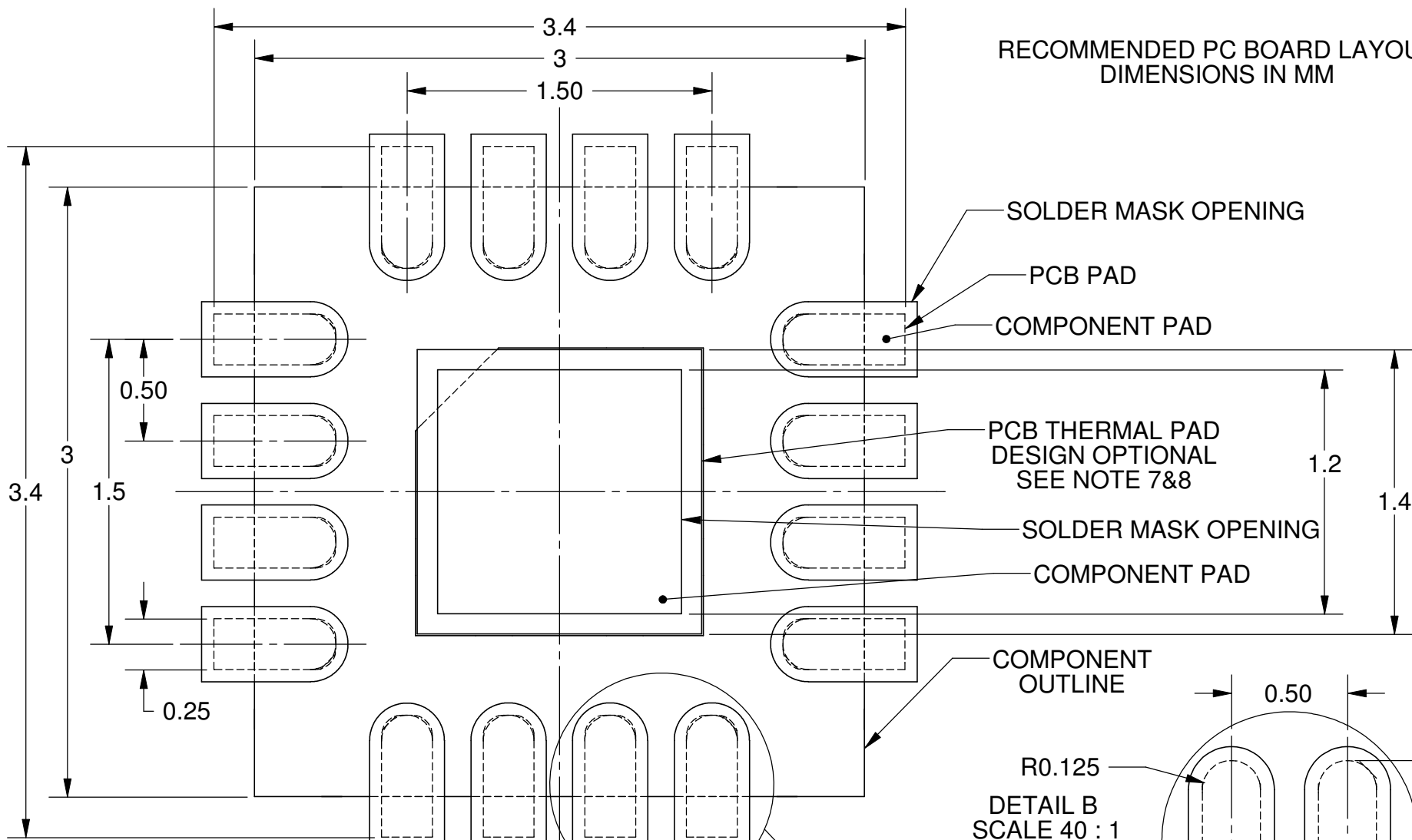
SHEET 2 OF 4

BONDING DIAGRAM

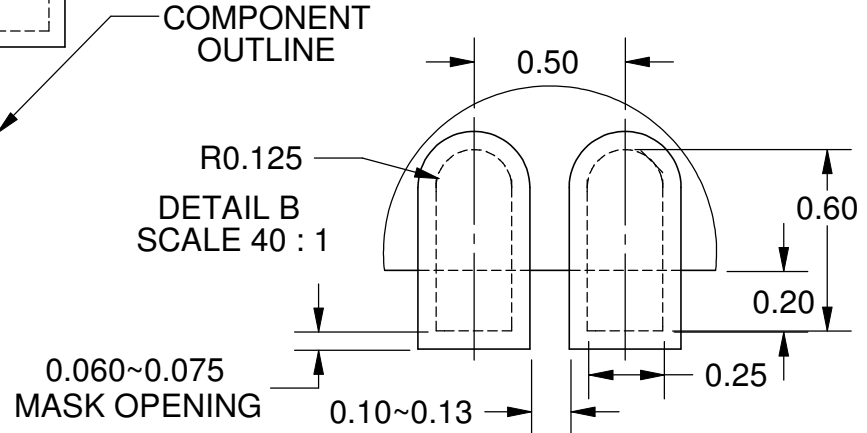


			
TITLE 16-LEAD 3mm P=0.5 mm M-QFN CAVITY PACKAGE			
SCALE 40:1	SIZE A	DRAWING NO. 451660	REV A
DO NOT SCALE DRAWING		SHEET 3 OF 4	

RECOMMENDED PC BOARD LAYOUT
DIMENSIONS IN MM



- Notes: (Unless Otherwise Specified).
- DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN KNOWLEDGE BASE WHEN DESIGNING THE PCB.
 - SURROUND EACH SIDE OF I/O PERIMETER PADS WITH 0.060~0.075 mm (NSMD) SOLDER MASK OPENING (2.4~3.0mils). OPTIONALLY OK TO USE RECTANGLE (NSMD) MASK OPENING AROUND I/O PADS.
 - ROUNDED PCB LAND PADS REDUCE SOLDER BRIDGING.
 - PCB LANDS SHOULD BE 0.2mm LONGER THEN THE PACKAGE I/O PADS.
 - THE WIDTH OF PERIMETER PCB PADS SHOULD MATCH (1:1) THE SAME WIDTH AS THE PACKAGE PADS.
 - REFER TO INDUSTRY REFERENCES SUCH AS IPC-SM-782 FOR PCB LAND PATTERN DESIGN.
 - THERMAL GROUND PADS MAY BE CHANGED TO SUITE REQUIREMENTS OF THE DESIGNER.
 - MAKE COPPER THERMAL PAD AS LARGE AS POSSIBLE.
 - DRILL MULTIPLE THERMAL VIAS 0.25~0.33mm DIAMETER USING 0.8~1.2mm PITCH GRID.
 - PLATE THERMAL VIA BARRELS WITH 1-OUNCE COPPER (18µm).
 - TENT (COVER) THERMAL VIAS WITH SOLDER MASK 0.1mm LARGER THEN THE VIA DIAMETER.
 - STENCIL DESIGN MAY BE CHANGED TO SUITE REQUIREMENTS OF THE DESIGNER.
 - LASER CUT STENCIL 0.125mm (5mil) THICK. APERTURE SIZE-TO-LAND RATIO OF 1:1.
 - THE SOLDER PASTE OPENING IN THE THERMAL PAD AREA SHOULD BE A MATRIX ARRAY OF SMALLER APERTURES INSTEAD OF ONE LARGE APERTURE TO CONTROL PASTE AMOUNTS.
 - APPLY 50% TO 80% SOLDER PASTE COVERAGE IN THE THERMAL PAD AREA.



Mirror Semiconductor™			
TITLE 16-LEAD 3mm P=0.5mm M-QFN CAVITY PACKAGE			
SCALE	SIZE	DRAWING NO.	REV
35:1	A	451660	A
DO NOT SCALE DRAWING			SHEET 4 OF 4